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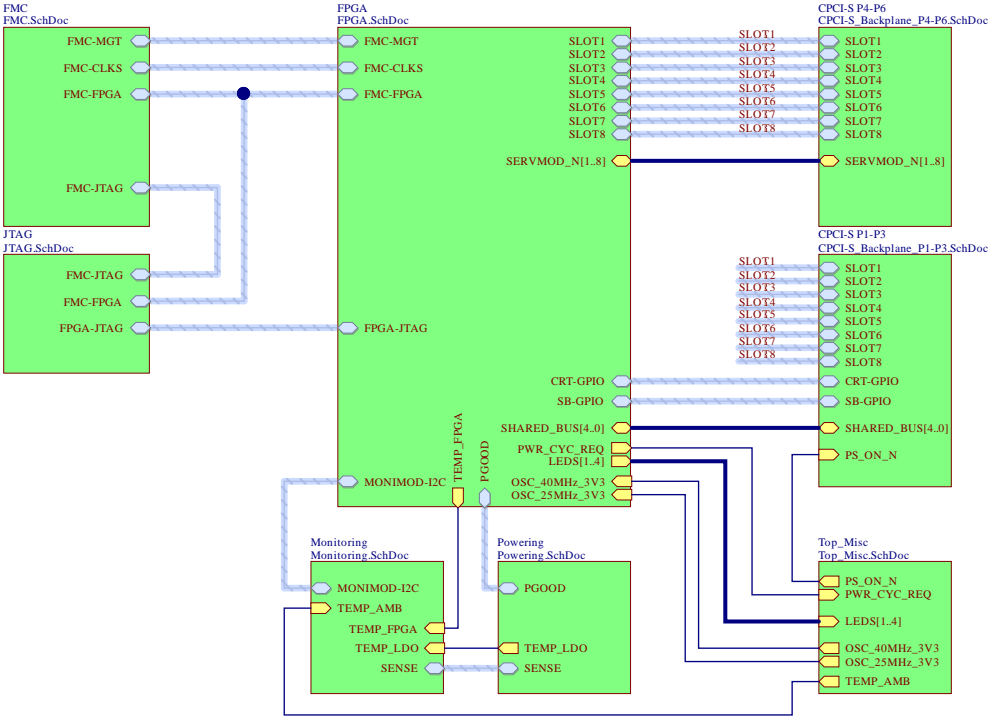
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Source location: <https://www.ohwr.org/project/diot-sb-ig1>

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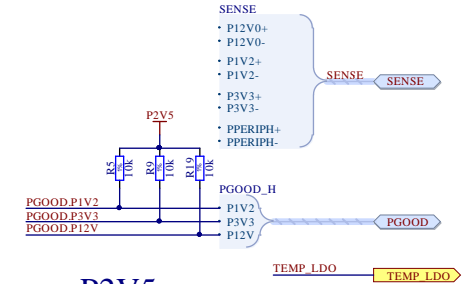
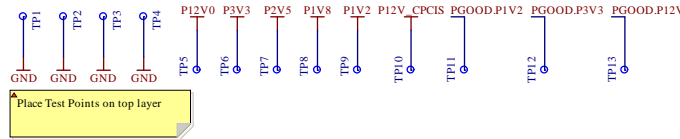
Project/Equipment		DI/OT	
Document		Designer	C. Gentsos
		Drawn by	C. Gentsos
		Check by	*
		Last Mod.	C. Gentsos
		File	DIOT-sb-ig1_top.SchDoc
		Print Date	01/10/2020 12:00:24
		Sheet	1 of 17
		Size	A3
		Rev	*

DI/OT Rad-tol System Board
Top Level

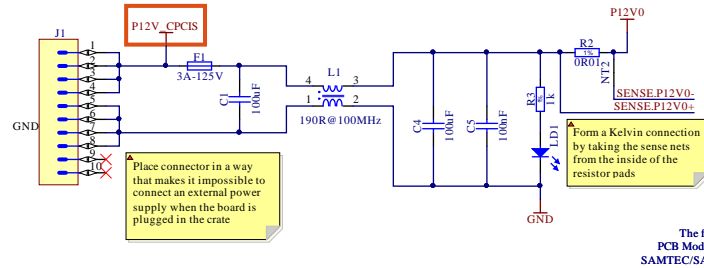
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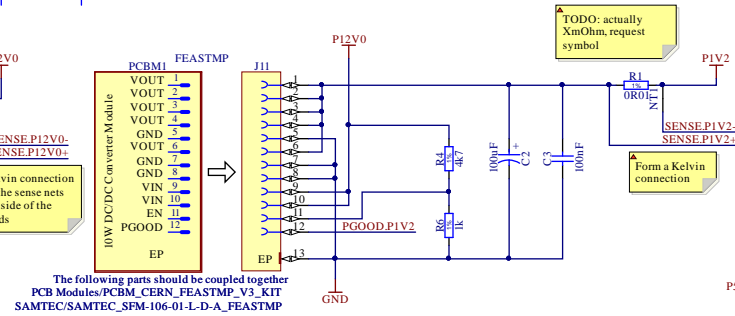
Test points



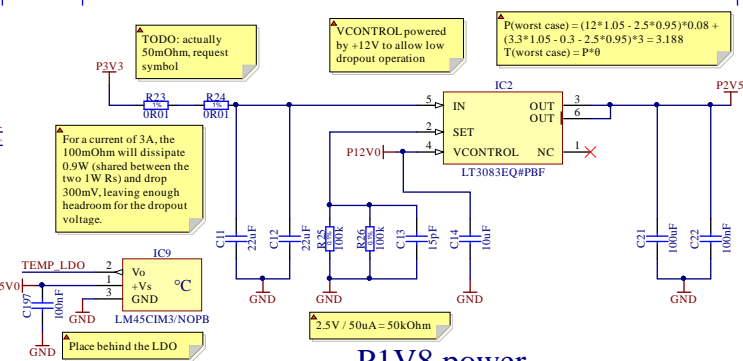
12V0 power cleanup



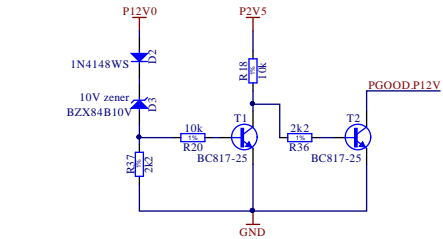
P1V2 power



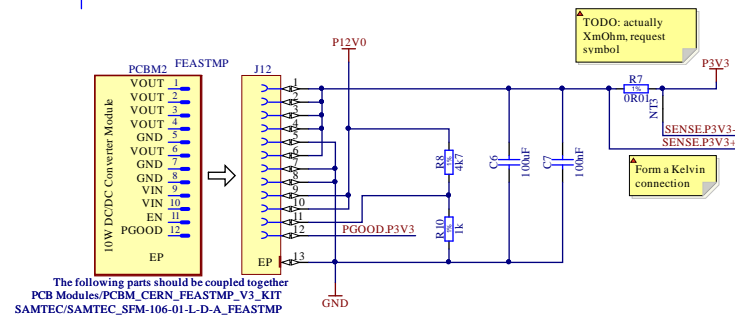
P2V5 power



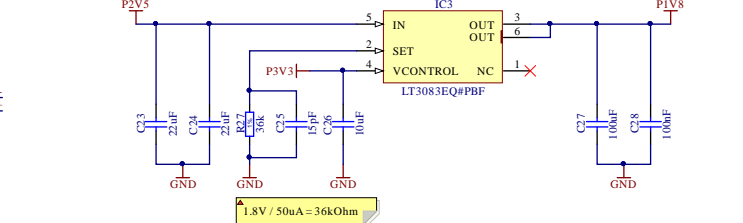
12V brownout detection



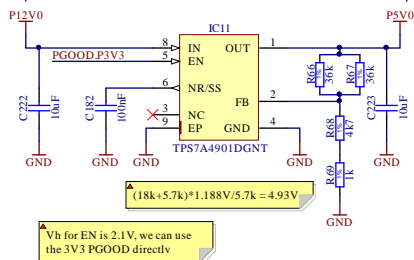
P3V3 power



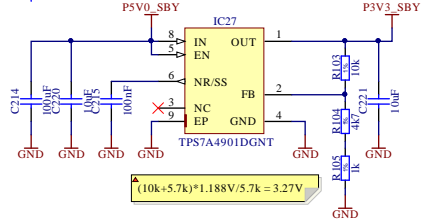
P1V8 power



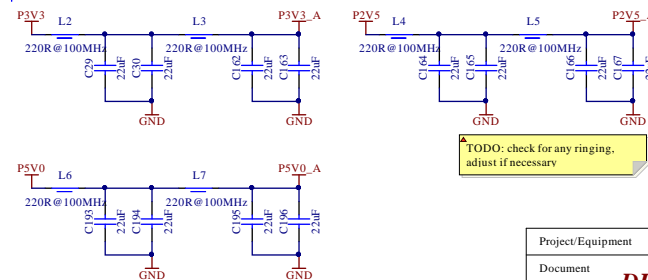
P5V0 power



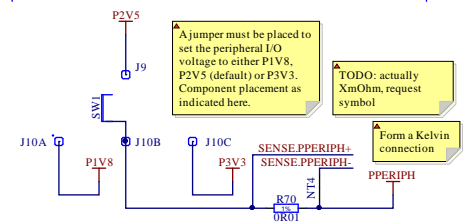
Always-on P3V3 power



Analog power filtering



Peripheral voltage selection



Project/Equipment	DIOT	Designer	C. Gentsos	28/08/2020
Document		Drawn by	C. Gentsos	28/08/2020
BE/CO		Check by	*	28/09/2020
		Last Mod.	C. Gentsos	28/09/2020
		File	Powering_SchDoc	
		Print Date	01/10/2020 12:00:25	Sheet 2 of 17
				A3

DIOT Rad-tol System Board
Power

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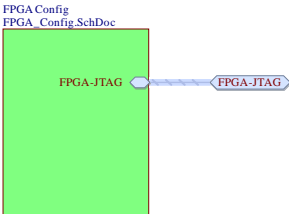
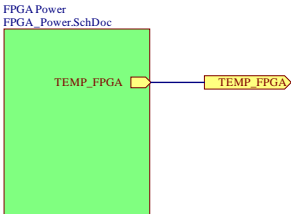
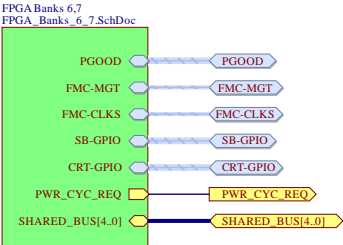
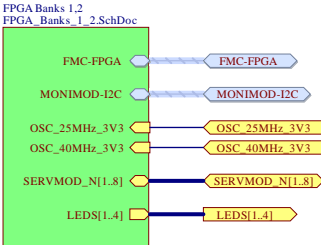
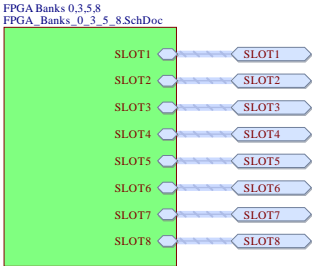
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Document		Designer	C. Gentsos
		Drawn by	C. Gentsos
		Check by	*
		Last Mod.	C. Gentsos
		File	FPGA.SchDoc
		Print Date	01/10/2020 12:00:25
		Sheet	3 of 17
		Size	A3
		Rev	*

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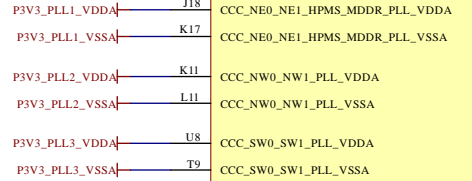
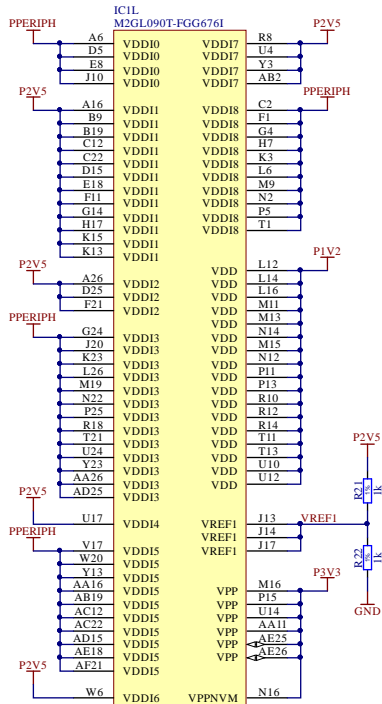
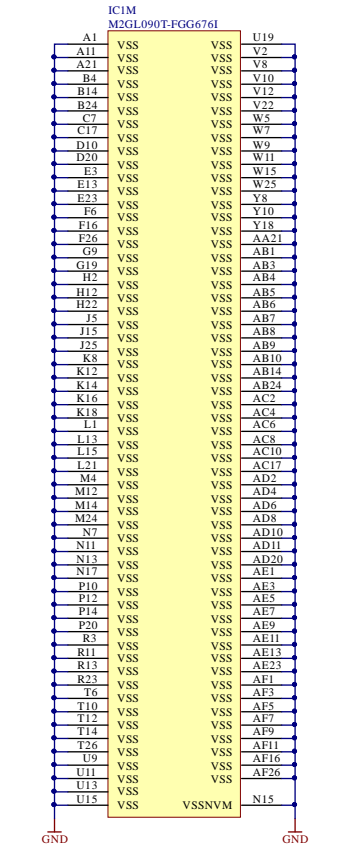
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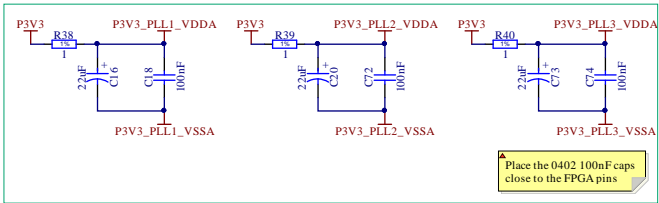
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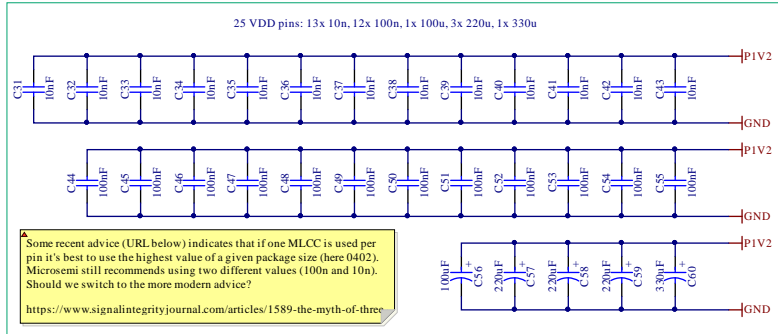
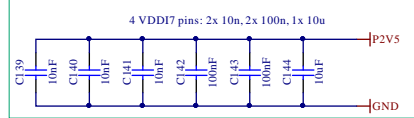
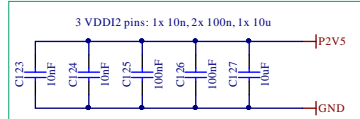
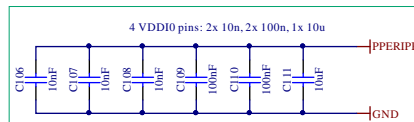
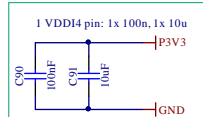
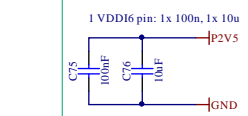
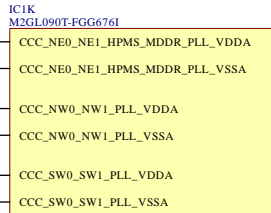
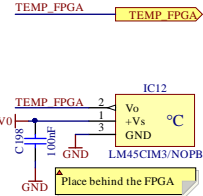


TODO: PLL-power, 2.5V or 3.3V? 2.5V will be smoother due to the LDO so better jitter but which one is better for radiation?

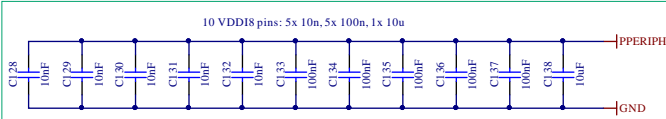
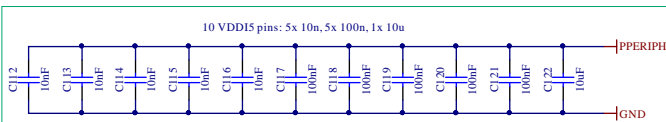
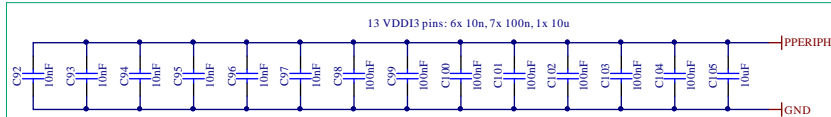
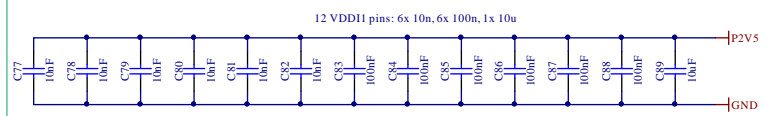
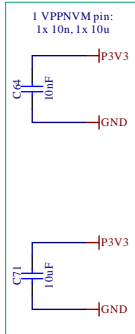
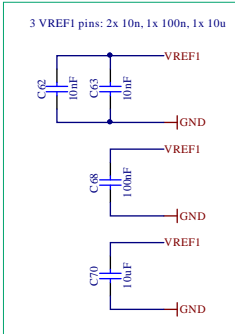
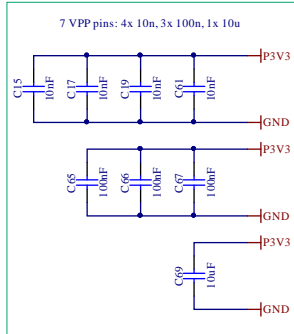
VPPNVM must be shorted to VPP



Place the 0402 100nF caps close to the FPGA pins



Some recent advice (URL below) indicates that if one MLCC is used per pin it's best to use the highest value of a given package size (here 0402). Microsemi still recommends using two different values (100n and 10n). Should we switch to the more modern advice?
<https://www.signalintegrityjournal.com/articles/1589-the-myth-of-three>



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Document	BE/CO	Drawn by	C. Gentsos	28/09/2020
		Check by	*	28/09/2020
		Last Mod.	C. Gentsos	28/09/2020
		File	FPGA_PowerSchDoc	4 of 17
		Print Date	01/10/2020 12:00:26	Sheet 4 of 17
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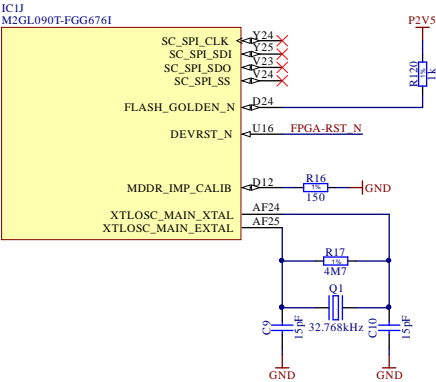
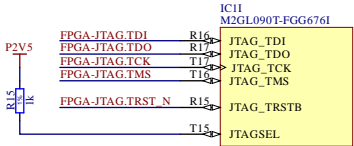
Source location: <https://www.ohwr.org/project/diot-sb-ig1>

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Parts powered by 2.5V

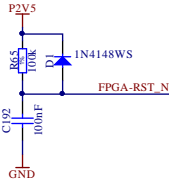


The JTAG and configuration pins are referred to as Bank 4



TODO: calibration not required so 0R may be acceptable, to be clarified.

This is to trigger a reprogram from the flash, assuming that



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Document		Designer C. Gentsos	
		Drawn by C. Gentsos	
		Check by *	
		Last Mod. C. Gentsos	
		File FPGA_Config.SchDoc	
		Print Date 01/10/2020 12:00:27	
		Sheet 5 of 17	
		Rev *	
		A3 *	

BE/CO

DI/OT Rad-tol System Board
FPGA Configuration

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Banks powered by 2.5V

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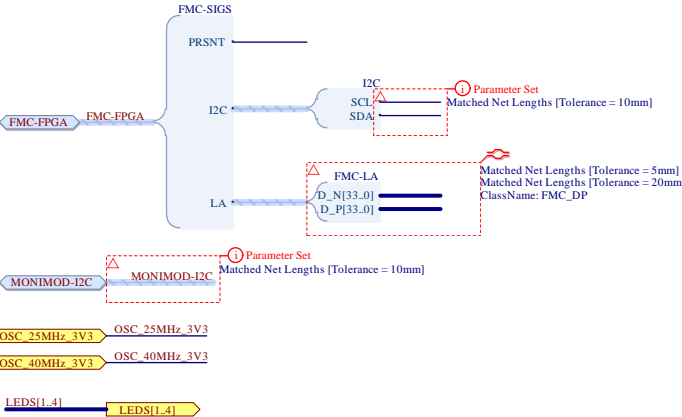
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Careful with pin swapping: the P nets of the differential pairs 0, 1, 17 and 18 are connected to clock-capable pins and can't be swapped with the other I/Os.

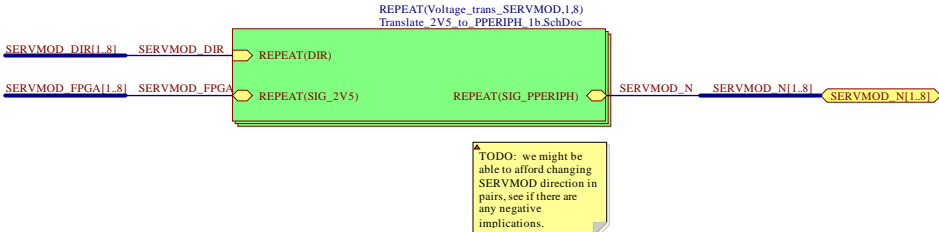
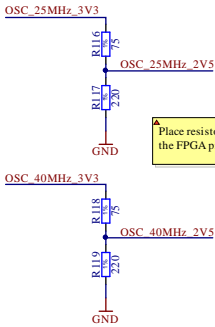
IC1B
M2GL090T-FGG6761

BANK 1	DDRIO62NB1/MDDR_ADDR15	C23	FMC-FPGA.L.A.D_N14
	DDRIO62PB1/MDDR_ADDR14	C22	FMC-FPGA.L.A.D_P14
	DDRIO63NB1/MDDR_ADDR15	C23	FMC-FPGA.L.A.D_N15
	DDRIO63PB1/MDDR_ADDR12	C23	FMC-FPGA.L.A.D_P15
	DDRIO64NB1/MDDR_ADDR11	C21	FMC-FPGA.L.A.D_N2
	DDRIO64PB1/MDDR_ADDR10	C20	FMC-FPGA.L.A.D_N3
	DDRIO65NB1/MDDR_ADDR9	C20	FMC-FPGA.L.A.D_P3
	DDRIO65PB1/MDDR_ADDR8	C22	FMC-FPGA.L.A.D_N4
	DDRIO66NB1/MDDR_ADDR7	C22	FMC-FPGA.L.A.D_P4
	DDRIO67NB1/MDDR_ADDR6	C18	FMC-FPGA.L.A.D_N5
	DDRIO67PB1/MDDR_ADDR5	C18	FMC-FPGA.L.A.D_P5
	DDRIO68NB1/MDDR_ADDR4	C21	FMC-FPGA.L.A.D_N6
	DDRIO68PB1/MDDR_ADDR3	C21	FMC-FPGA.L.A.D_P6
	DDRIO69NB1/MDDR_ADDR2	C19	FMC-FPGA.L.A.D_N7
	DDRIO69PB1/MDDR_ADDR1	C19	FMC-FPGA.L.A.D_P7
	DDRIO70NB1/MDDR_ADDR0	C18	FMC-FPGA.L.A.D_N8
	DDRIO70PB1/MDDR_BA2	C17	FMC-FPGA.L.A.D_P8
	DDRIO71NB1/MDDR_BA1	C20	FMC-FPGA.L.A.D_N9
	DDRIO71PB1/MDDR_BA0	C20	FMC-FPGA.L.A.D_P9
	DDRIO72NB1/MDDR_CLK_N	C20	FMC-FPGA.L.A.D_N10
	DDRIO72PB1/MDDR_CLK_N	C19	FMC-FPGA.L.A.D_P10
	DDRIO73NB1/MDDR_CAS_N	C19	FMC-FPGA.L.A.D_N11
	DDRIO73PB1/MDDR_RESET_N	C18	FMC-FPGA.L.A.D_P11
	DDRIO74NB1/MDDR_CS_N	C17	FMC-FPGA.L.A.D_N12
	DDRIO74PB1/MDDR_CKE	C16	FMC-FPGA.L.A.D_P12
	DDRIO75NB1/MDDR_WE_N	C16	FMC-FPGA.L.A.D_N13
	DDRIO75PB1/MDDR_RAS_N	C16	FMC-FPGA.L.A.D_P13
	DDRIO76NB1/MDDR_DQ15	C19	FMC-FPGA.L.A.D_N1
	DDRIO76PB1/CCC_NE1_CLK13/MDDR_DQ14	C18	FMC-FPGA.L.A.D_P1
	DDRIO77NB1/MDDR_DQ13	C18	FMC-FPGA.L.A.D_N12
	DDRIO77PB1/MDDR_DQ12/GB12/CCC_NE1_CLK12	C15	FMC-FPGA.L.A.D_P0
	DDRIO78NB1/MDDR_DM_RDQS1	C16	FMC-FPGA.L.A.D_N16
	DDRIO78PB1/MDDR_TMATCH_0_IN	C17	FMC-FPGA.L.A.D_P16
	DDRIO79NB1/MDDR_DQS1_N	C16	FMC-FPGA.L.A.D_N17
	DDRIO79PB1/MDDR_DQS1/GB8/CCC_NE0_CLK13	C17	FMC-FPGA.L.A.D_P17
	DDRIO80NB1/MDDR_DQ11	C16	FMC-FPGA.L.A.D_N18
	DDRIO80PB1/MDDR_DQ10/CCC_NE0_CLK12	C16	FMC-FPGA.L.A.D_P18
	DDRIO81NB1/MDDR_DQ9	C16	FMC-FPGA.L.A.D_N19
	DDRIO81PB1/MDDR_DQ8	C15	FMC-FPGA.L.A.D_P19
	DDRIO82NB1/MDDR_TMATCH_0_OUT	C15	FMC-FPGA.L.A.D_N20
	DDRIO82PB1/MDDR_DQ7	C15	FMC-FPGA.L.A.D_P20
	DDRIO83NB1/MDDR_DQ6	C16	FMC-FPGA.L.A.D_N21
	DDRIO83PB1/MDDR_DQ5	C15	FMC-FPGA.L.A.D_P21
	DDRIO84NB1/MDDR_DQ4	C15	FMC-FPGA.L.A.D_N22
	DDRIO84PB1/MDDR_DM_RDQS0	C14	FMC-FPGA.L.A.D_P22
	DDRIO85NB1/MDDR_DQS0_N	C15	FMC-FPGA.L.A.D_N23
	DDRIO85PB1/MDDR_DQS0	C14	FMC-FPGA.L.A.D_P23
	DDRIO86NB1/MDDR_DQ3	C14	FMC-FPGA.L.A.D_N24
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	DDRIO87PB1/MDDR_DQ0	C13	FMC-FPGA.L.A.D_P25
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	DDRIO89NB1/MDDR_DQ_ECC0	C13	FMC-FPGA.L.A.D_N27
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	DDRIO93NB1/CCC_NW0_CLK12	C13	FMC-FPGA.L.A.D_N31
	DDRIO93PB1/MDDR_TMATCH_ECC_OUT	C14	FMC-FPGA.L.A.D_P31
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	DDRIO94PB1	C11	FMC-FPGA.L.A.D_P32
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	DDRIO96NB1	C10	FMC-FPGA.L.A.D_N34
	DDRIO96PB1	C10	FMC-FPGA.L.A.D_P34
	DDRIO97NB1	C12	SERVMOD_DIR1
	DDRIO97PB1	C11	SERVMOD_DIR2
	DDRIO98NB1	C9	SERVMOD_DIR3
	DDRIO98PB1	C10	SERVMOD_DIR4
	DDRIO99NB1	C10	SERVMOD_DIR5
	DDRIO99PB1	C9	SERVMOD_DIR6



IC1C
M2GL090T-FGG6761

BANK 2	MSIO51NB2	F25	SERVMOD_DIR7
	MSIO51PB2	F26	SERVMOD_DIR8
	MSIO52NB2	F26	OSC_25MHz_2V5
	MSIO52PB2/CCC_NE0_CLK11	F25	OSC_40MHz_2V5
	MSIO53NB2	F26	OSC_25MHz_2V5
	MSIO53PB2/CCC_NE1_CLK11	F26	OSC_40MHz_2V5
	MSIO54NB2	F24	LED51
	MSIO54PB2/GB10/VCCC_SE0_CLK1	F25	LED52
	MSIO55NB2	F24	LED53
	MSIO55PB2/GB14/VCCC_SE1_CLK1	F24	LED54
	MSIO56NB2	G23	SERVMOD_FPGA1
	MSIO56PB2	G23	SERVMOD_FPGA2
	MSIO57NB2	G24	SERVMOD_FPGA3
	MSIO57PB2	G25	SERVMOD_FPGA4
	MSIO58NB2	G24	SERVMOD_FPGA5
	MSIO58PB2	G25	SERVMOD_FPGA6
	MSIO59NB2	G23	FMC-FPGA.PRSNT
	MSIO60NB2	F22	SERVMOD_FPGA7
	MSIO60PB2	F22	SERVMOD_FPGA8
	MSIO61NB2	G20	MONIMOD-I2C.SCL
	MSIO61PB2	G21	MONIMOD-I2C.SDA



Project/Equipment		DI/OT	
Document		Designer C. Gentsos	
BE/CO		Drawn by C. Gentsos	
CERN		Check by *	
		Last Mod. C. Gentsos	
		File FPGA_Banks_1_2.SchDoc	
		Print Date 01/10/2020 12:00:29	
		Sheet 7 of 17	
		A3 *	

DI/OT Rad-tol System Board
FPGA I/O Banks B1, B2

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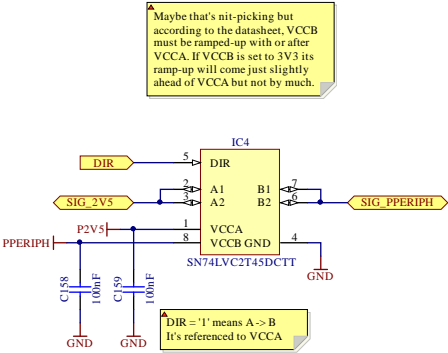
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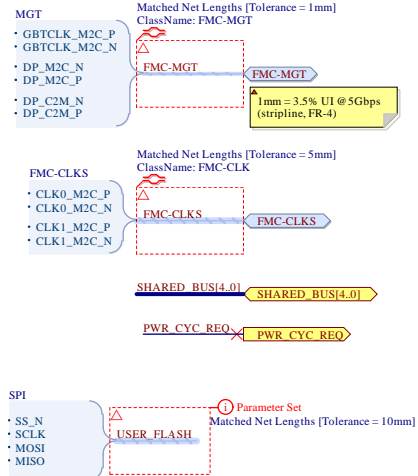
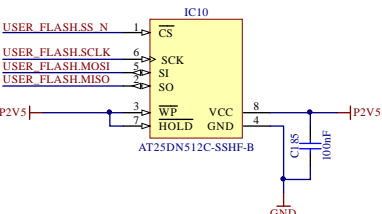
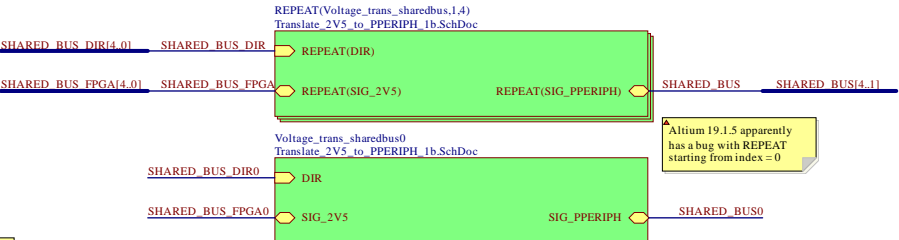
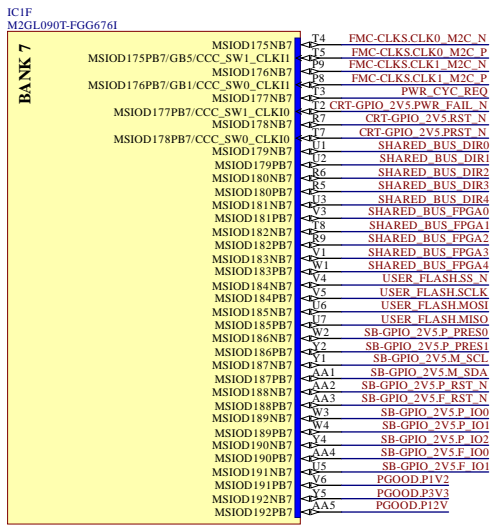
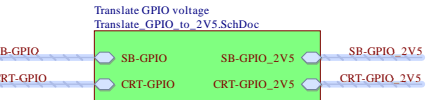
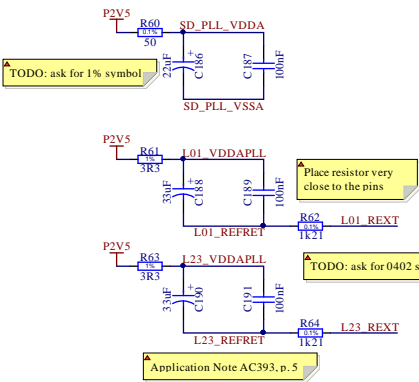
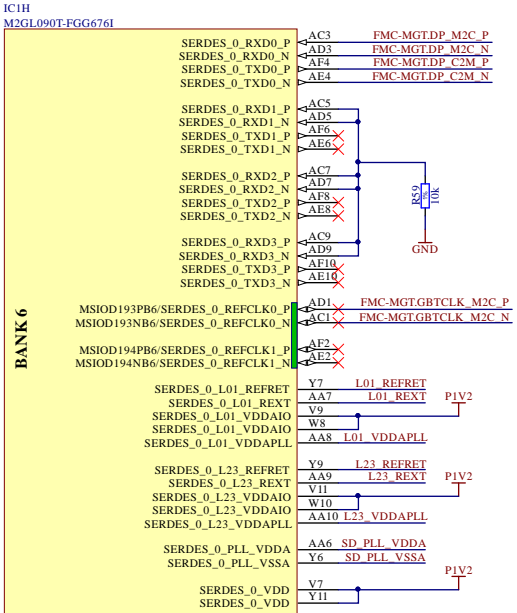
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Banks powered by 2.5V



Project/Equipment DI/OT			
Document		Designer C. Gentsos	28/08/2020
BE/CO		Drawn by C. Gentsos	28/08/2020
		Check by *	28/09/2020
		Last Mod. C. Gentsos	28/09/2020
		File FPGA_Banks_6_7.SchDoc	
		Print Date 01/10/2020 12:00:30	Sheet 9 of 17
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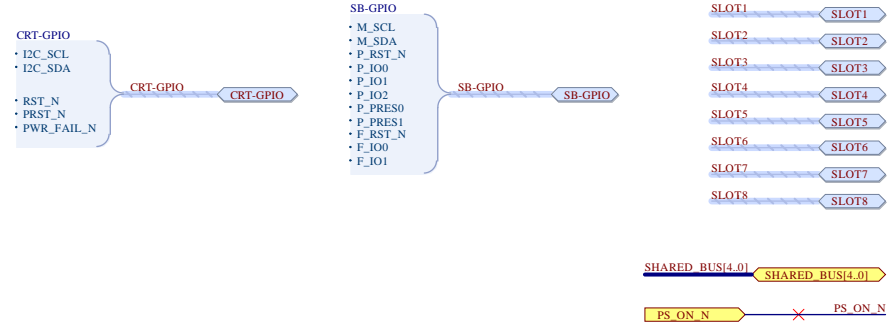
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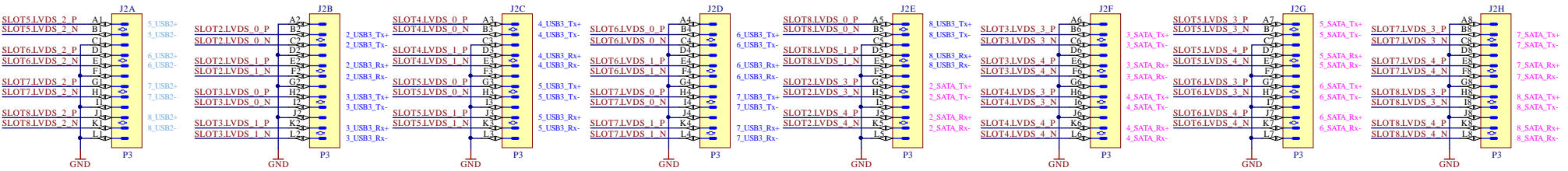
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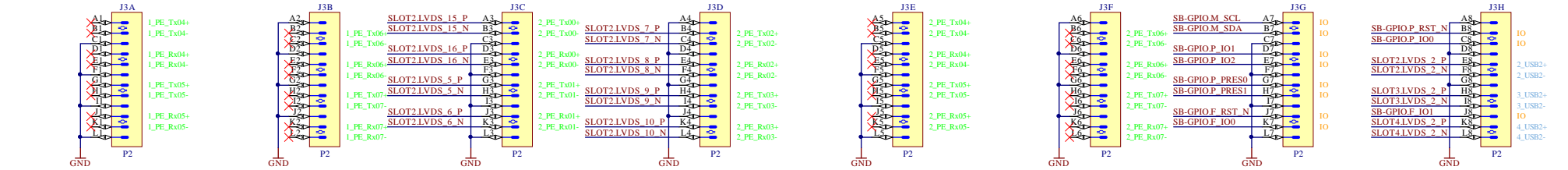
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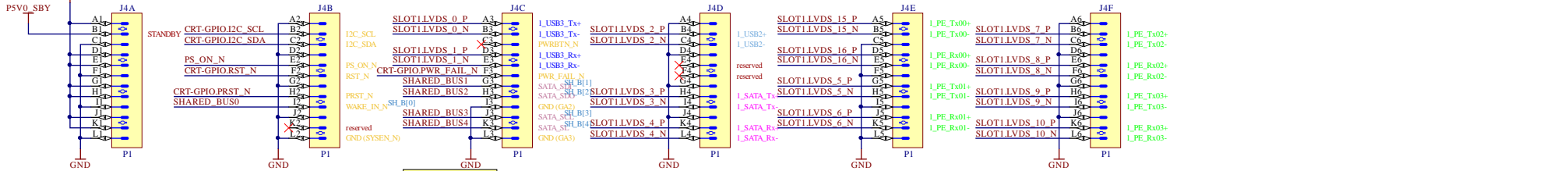
P3 Connector



P2 Connector



P1 Connector



TODO: how to handle PWRBTN?

n_{PE} Tx00 and n_{PE} Rx00 diff pairs can carry Multi-Gigabit signals (2.1.6). 1000Ohm impedance, 5mm tolerance

Project/Equipment		DIOT	
Document		Designer C. Gentsos	
BE/CO		Drawn by C. Gentsos	
CERN		Check by *	
DIOT Rad-tol System Board		Last Mod. C. Gentsos	
CPCI-S Backplane (1/2)		File CPCI-S Backplane_P1-P3.SchDoc	
Print Date 01/10/2020 12:00:32		Sheet 11 of 17	
European Organization for Nuclear Research		EDA-XXXXX-VX-X	
CH-1211 Genève 23 - Switzerland		A3	

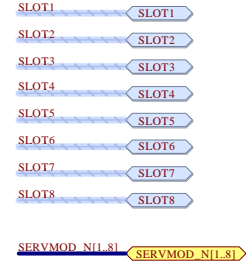
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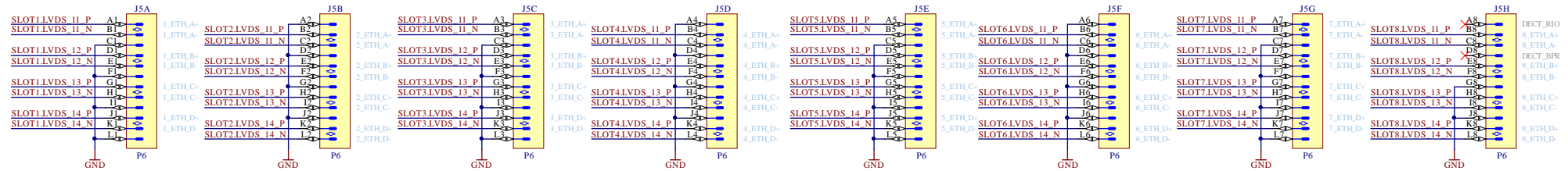
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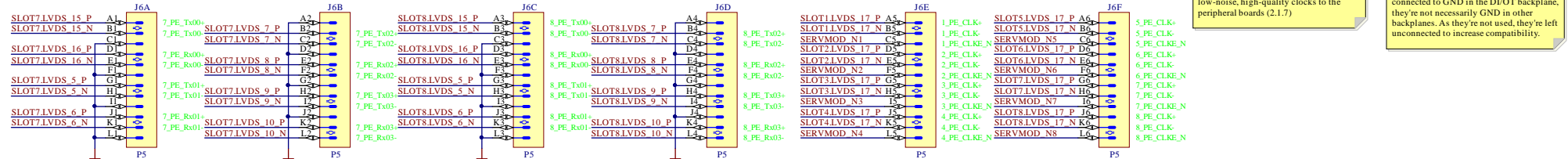
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P6 Connector



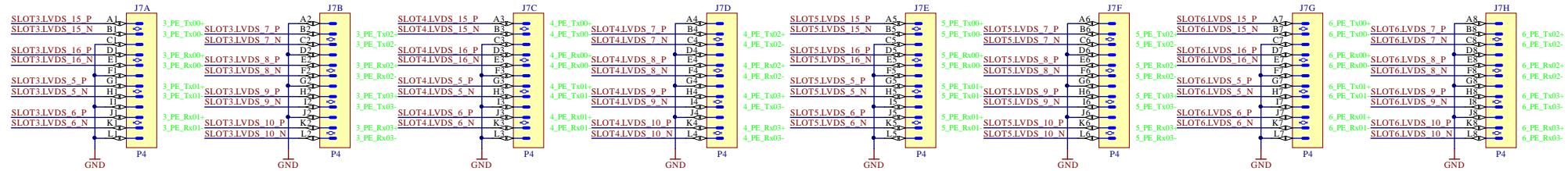
P5 Connector



1. PE_CLK diff pairs will provide low-noise, high-quality clocks to the peripheral boards (2.1.7)

The DECT_RIO and DECT_BPR pins are connected to GND in the DI/OT backplane, they're not necessarily GND in other backplanes. As they're not used, they're left unconnected to increase compatibility.

P4 Connector



Project/Equipment		DI/OT	
Document		Designer C. Gentsos	
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CERN		Check by *	
		Last Mod. C. Gentsos	
		File CPCL-S Backplane_P4-P6_SchDoc	
		Print Date 01/10/2020 12:00:33	
		Sheet 12 of 17	
		A3	

DI/OT Rad-tol System Board
CPCL-S Backplane (2/2)

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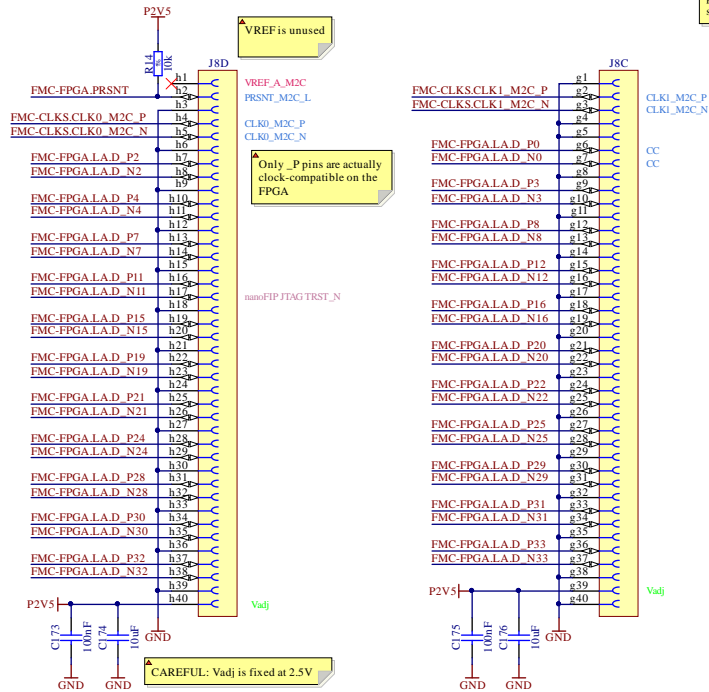
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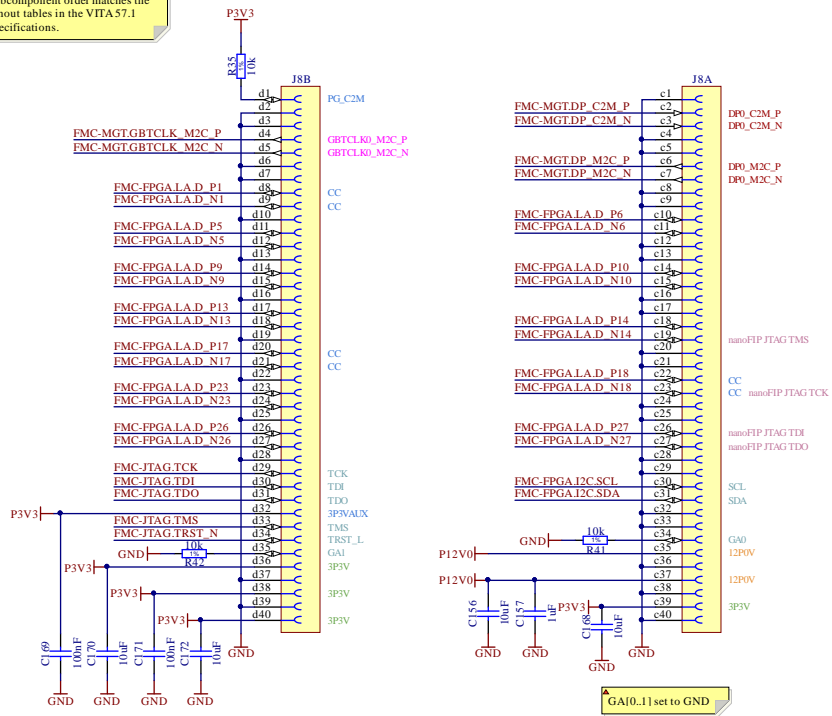
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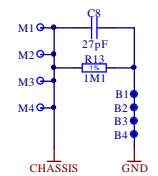
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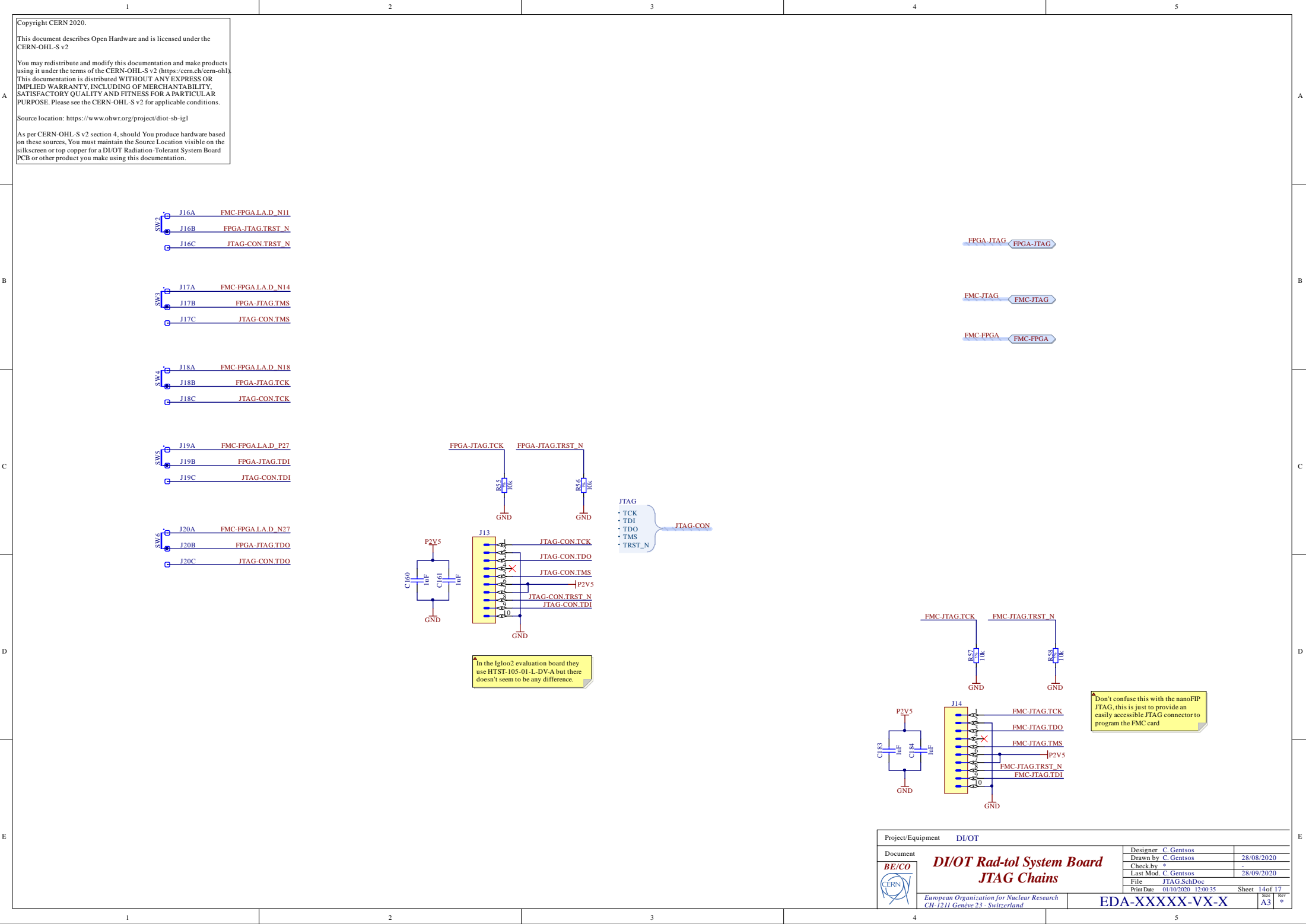
Subcomponent order matches the pinout tables in the VITA 57.1 specifications.



Front panel and FMC slot spacers



Project/Equipment		DI/OT	
Document		Designer C. Gentsos	
BE/CO		Drawn by C. Gentsos	
DI/OT Rad-tol System Board		28/08/2020	
FMC		Check by *	
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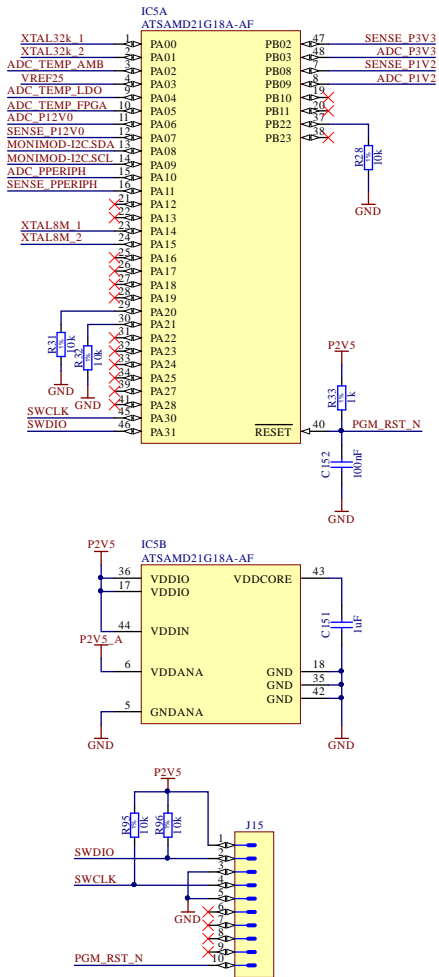
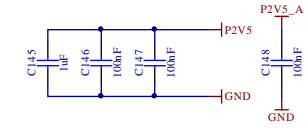
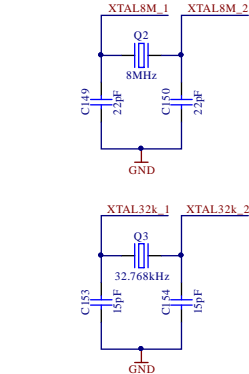
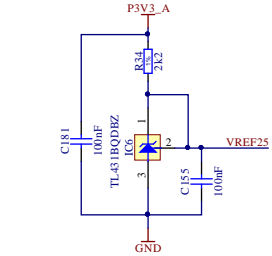
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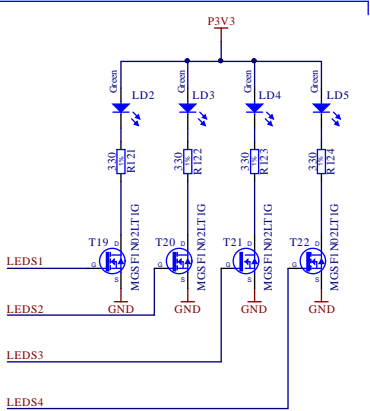
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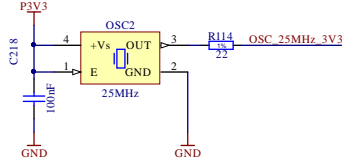
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User LEDs

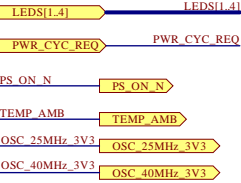
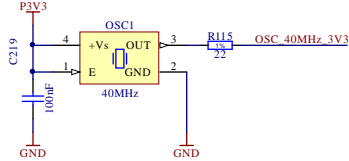


TODO: We have the pins, do we want to double the clocks in case someone likes redundancy?

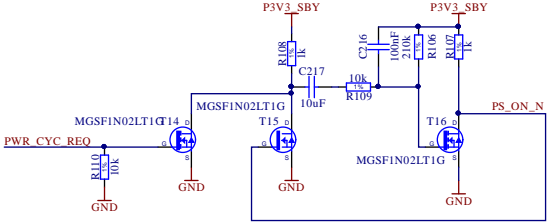
25MHz oscillator



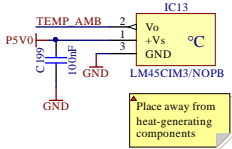
40MHz oscillator



Power cycle pulse generator

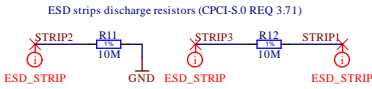


Ambient temp sensor



Place away from heat-generating components

ESD Protection



Project/Equipment		DI/OT	
Document		Designer	C. Gentsos
		Drawn by	C. Gentsos
		Check by	*
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		Print Date	01/10/2020 12:00:37
		Sheet	17 of 17
		Size	A3
		Rev	*

BE/CO

DI/OT Rad-tol System Board

Miscellaneous

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